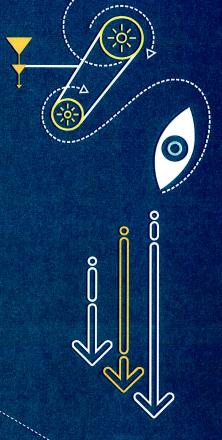
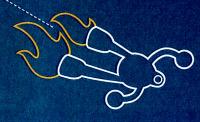
Liang-Kai Wang Staff Engineer, Qualcomm Technology Inc.

Hexagon DSP (QDSP6) Overview of Qualcomm

QUALCOMM[®]





QUALCOMM in Austin

- Qualcomm Technologies Inc. (QTI) is the
- Largest Fabless Manufacturer Since 2003
- Overall Semiconductor Industry Ranking in 2012: 3rd
- the Largest Global Manufacturer of Wireless Baseband ("Cell Phone") Chips
- QTI Sells ~170 Million Chipsets / Quarter
- Willie Anderson Leads QTI Austin Design Center
- QTI Austin Has Been Designing DSPs Since 2004
- 5 DSPs Designed in Austin, Now in Dozens of Chips

Source: IHS iSuppli, IC Insights' Strategic Review Database

Qualcomm Hexagon™ DSP

Robust Capability + Superior Power Efficiency

Snapdragon™ S4: MSM8960 Block Diagram



Architecture nexagon Processor Core-level System

- 4-issue VLIW with Interleave Hardware Threading
- 1~4+ instructions per cycle. Managed by software
- Dual 64-bit load/store units
- 8/16/32/64-bit ld/st, 32b scalar
- Dual 64-bit vector units
- 8/16/32/64-bit vectorized MPY/ALU/SHIFT/SP, Permute, Bit manipulation
- 16 8x8, Eight 16x16, Four 16x32, Two 32x32 or SP FP MACs/cycle
- Unified vector/scalar/floating-point register
- Compound instructions
- Fuse simple instructions
- Novel data-flow packets
- Intra-packet data forwarding enables single cycle load-compare-branch

Execution Unit of Hexagon

Powerful Execution Unit with Low Energy Consumption

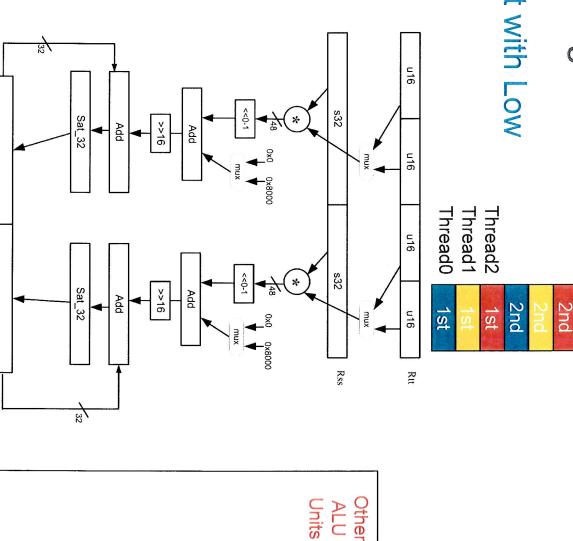
- Supported datatype:
- integer (signed/unsigned), fractional, and complex numbers
- Single precision floating point numbers
- Supported instructions in both scalar and vector torms
- Basic arithmetic instructions
- Floating point (compliant to IEEE 754-2008) and FP \integer convert instructions
- Hundreds of compound instructions
- Special-purpose instructions
- Focus on communications, audio, video, imaging

Execution Unit of Hexagon

3rd

Powerful Execution Unit with Low Energy Consumption

Hardware multitheading enables complex and compound instructions to be run in hardware



Rxx

*Animations are for illustration only

Frequency Performance from Work/Cycle, not

CIOCK				
- 100	16.6	4.070	245	Tensilica ConnX 545CK245
· Reculte: More work at low	6.4	2,140	335	CEVA TeakLite-III 335
 High clock rate design me 	<u>ö</u>	2,000	000	CEAN CEAN-V 1050330
out-of-order execution	0		300	0EVA 0EVA V1800
 Memory stalls: cache preference 	13.4	20,030	1,500	TI TMS320C66x1,500
parallel tag/data caches, e	11.0	13,170	1,200	TI TMS320C64x+1,200
 Speculation: branch predic 	18.1	12,660	700	V4 & V5 (3 threads) 700
operations				Qualcomm Hexagon
Opporations	18.1	4,220	233	V4 & V5 (1 thread) 233
 Elimination of power-hung 				Qualcomm Hexagon
	15.5	9,300	600	V2 (6 threads) 600
				Qualcomm Hexagon
מפוועפו ליפווטווושווכם שנוטו	15.5	1,550	100	V2 (1 thread) 100
dolivor porformance of lov				Qualcomm Hexagon
 Architecture evolution to 	max	max	max	
A	<u> </u>		per Thread	(siligle core)
 Hexagon processor 	BDTImark2000	BDTImark2000	Clock Rate (MHz)	Fixed-Point Processors

- 80
- Jgry
- etc.
- efetch,
- ethods
- Lower energy for same Wer

performance

Conclusion

- Power consumption and Performance are important in
- By working with GPU and CPU seamlessly, Hexagon DSP is designed to provides the low energy footprint while enables massive data and control processing power mobile space

Acknowledgement

Anderson (VP), Rick Maule (Product Management), QDSP6 Codrescu, Erich Plondke, et al.), Physical Design Team Thanks for the support, slides and documents from Willie Logic Team (Allan Lester, et al.), Architecture Team (Lucian (Rowland Reed, et al.) (Paul Bassett, Dwight Galbi, et al.), and Verification Team